

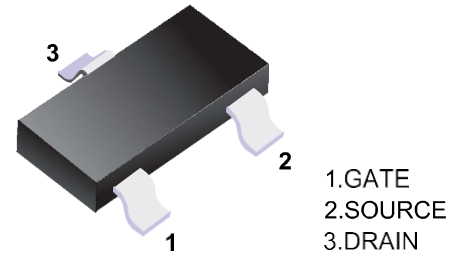
■ High Speed Switching Applications

- ESD protected gate
- Low ON-resistance

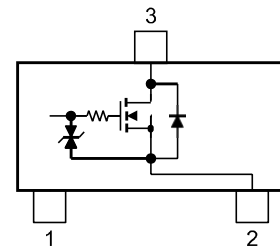
$R_{DS(on)} = 2.8 \Omega$ (typ.) (@ $V_{GS} = 10 V$)

$R_{DS(on)} = 3.1 \Omega$ (typ.) (@ $V_{GS} = 5 V$)

$R_{DS(on)} = 3.2 \Omega$ (typ.) (@ $V_{GS} = 4.5 V$)



■ Simplified outline(SOT-23)



Equivalent Circuit (top view)

Absolute Maximum Ratings (Ta = 25°C)

Characteristic		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	60	V
Gate-source voltage		V_{GSS}	± 20	V
Drain current (Note1)	DC	I_D	200	mA
	Pulse	I_{DP} (Note 2)	760	
Power dissipation		P_D (Note 3)	320	mW
		P_D (Note 4)	1000	
Channel temperature		T_{ch}	150	°C
Storage temperature		T_{stg}	-55 to 150	°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: The channel temperature should not exceed 150°C during use.

Note 2: Pulse width ≤ 10 μs, Duty ≤ 1%

Note 3: Mounted on an FR4 board
(25.4 mm × 25.4 mm × 1.6 mm, Cu Pad: 0.42 mm² x 3)

Note 4: Mounted on an FR4 board
(25.4 mm × 25.4 mm × 1.6 mm, Cu Pad: 645 mm²)



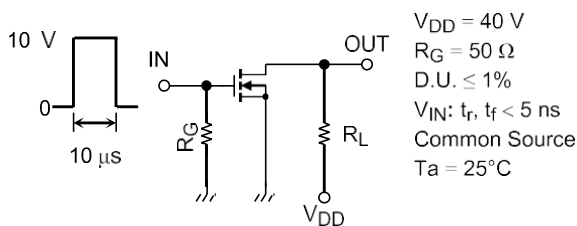
Electrical Characteristics (Ta = 25°C, Otherwise specified)

Characteristic	Symbol	Test Condition	Min	Typ.	Max	Unit	
Drain-source breakdown voltage	$V_{(BR)DSS}$	$I_D = 250 \mu A, V_{GS} = 0 V$	60	—	—	V	
Drain cutoff current	I_{DSS}	$V_{DS} = 60 V, V_{GS} = 0 V$	—	—	1	μA	
		$V_{DS} = 60 V, V_{GS} = 0 V, T_J = 150^\circ C$	—	—	200		
Gate leakage current	I_{GSS}	$V_{GS} = \pm 16 V, V_{DS} = 0 V$	—	—	± 2	μA	
		$V_{GS} = \pm 10 V, V_{DS} = 0 V$	—	—	± 0.5		
		$V_{GS} = \pm 5 V, V_{DS} = 0 V$	—	—	± 0.1		
Gate threshold voltage	V_{th}	$I_D = 250 \mu A, V_{DS} = V_{GS}$	1.1	—	2.1	V	
Forward transfer admittance	$ Y_{fs} $	$V_{DS} = 10 V, I_D = 200 mA$ (Note 5)	—	450	—	mS	
Drain-source ON-resistance	$R_{DS(ON)}$ (Note 5)	$I_D = 100 mA, V_{GS} = 10 V$	—	2.8	3.9	Ω	
		$I_D = 100 mA, V_{GS} = 10 V, T_J = 150^\circ C$	—	5.4	8.1		
		$I_D = 100 mA, V_{GS} = 5 V$	—	3.1	4.4		
		$I_D = 100 mA, V_{GS} = 4.5 V$	—	3.2	4.7		
Total Gate Charge	$Q_{G(tot)}$	$V_{DS} = 30 V, I_D = 200 mA$ $V_{GS} = 4.5 V$	—	0.27	0.35	nC	
Gate-Source Charge	Q_{GS}		—	0.08	—		
Gate-Drain Charge	Q_{GD}		—	0.08	—		
Input capacitance	C_{iss}	$V_{DS} = 10 V, V_{GS} = 0 V, f = 1 MHz$	—	11	17	pF	
Output capacitance	C_{oss}		—	3	—		
Reverse transfer capacitance	C_{rss}		—	0.7	—		
Switching time	Turn-on delay time	$t_{d(on)}$	$V_{DD} = 40 V, I_D = 160 mA$ $V_{GS} = 0 V \text{ to } 10 V, R_G = 50 \Omega$	—	2	4	ns
	Rise time	t_r		—	3	—	
	Turn-off delay time	$t_{d(off)}$		—	7	14	
	Fall time	t_f		—	24	—	
Drain-source forward voltage	V_{DSF}	$I_D = -115 mA, V_{GS} = 0 V$ (Note 5)	—	-0.87	-1.2	V	

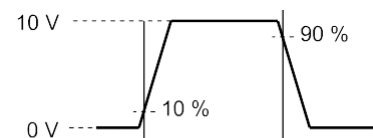
Note 5: Pulse test

Switching Time Test Circuit

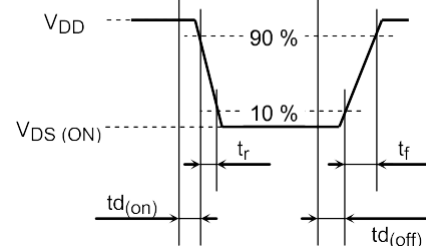
(a) Test Circuit

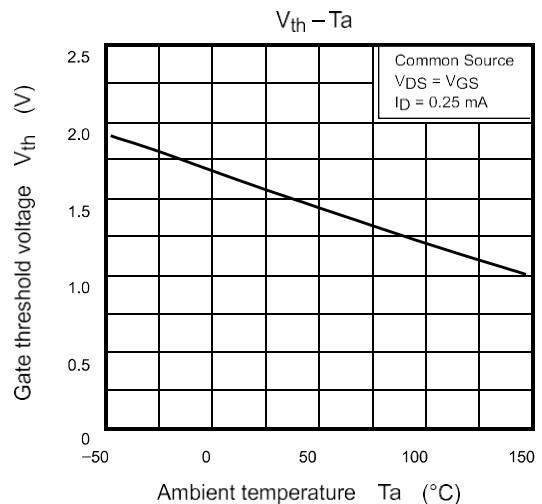
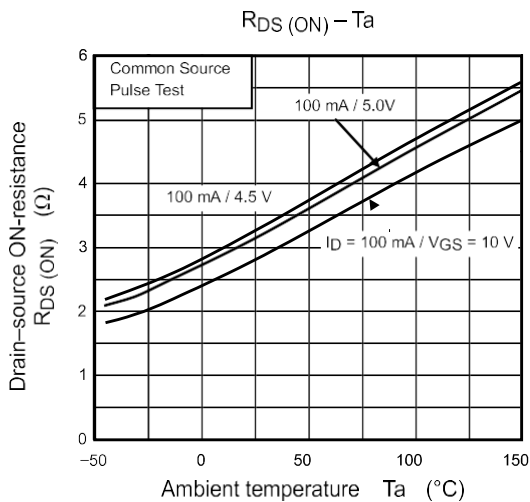
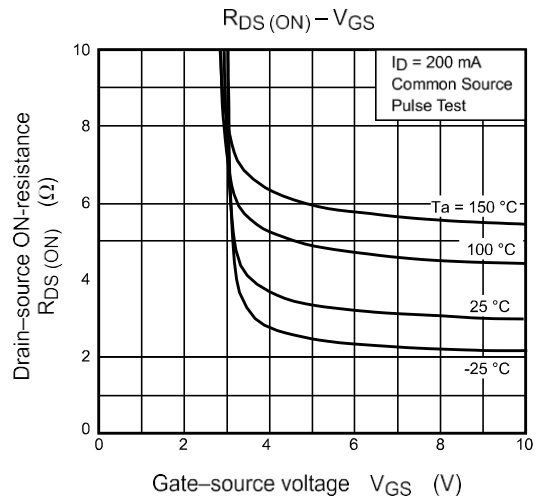
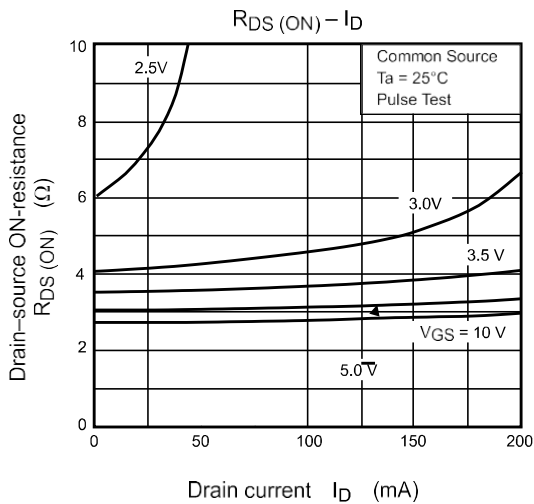
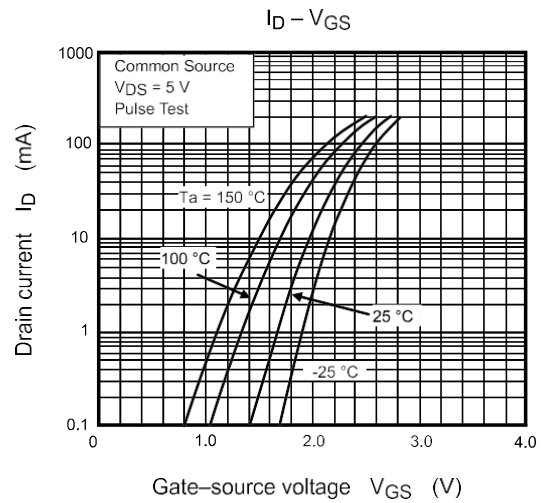
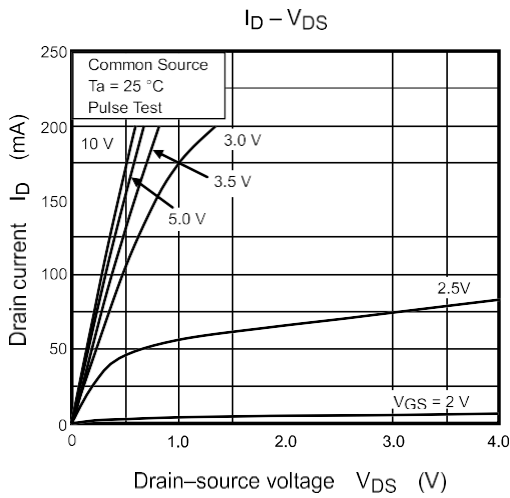


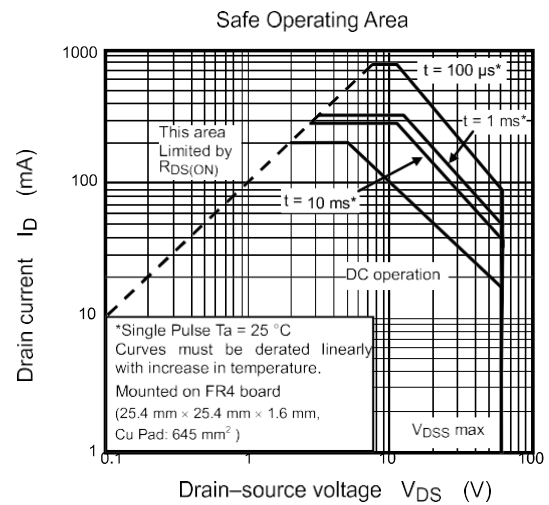
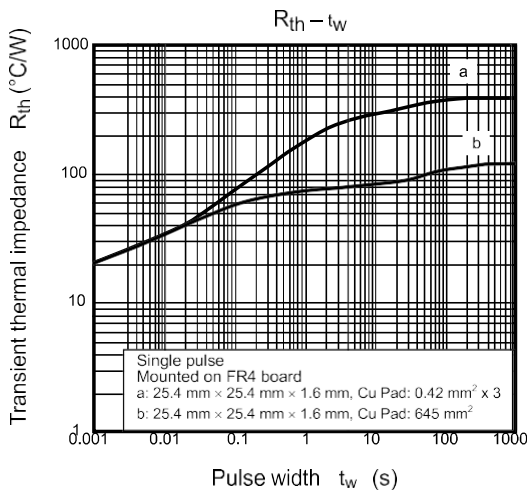
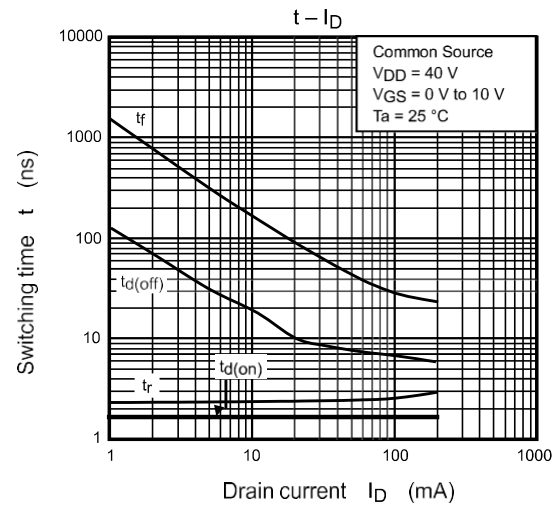
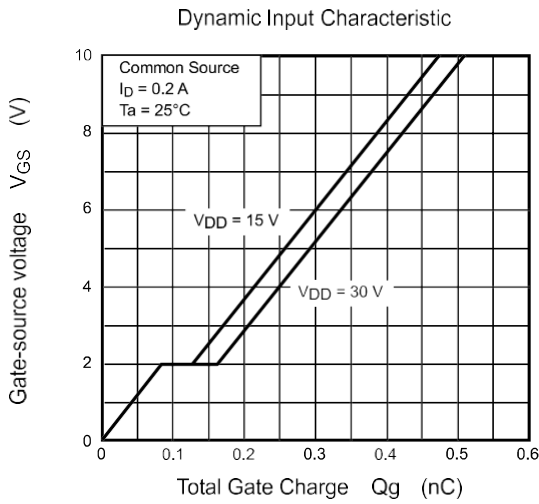
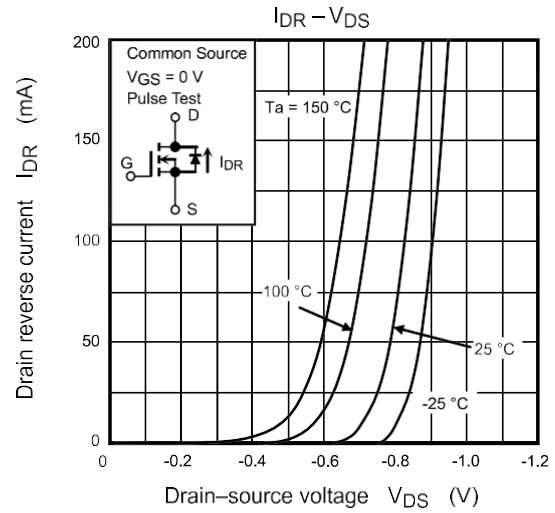
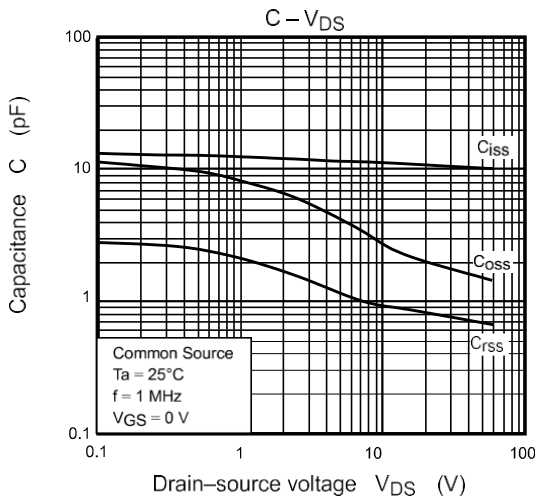
(b) V_{IN}



(c) V_{OUT}



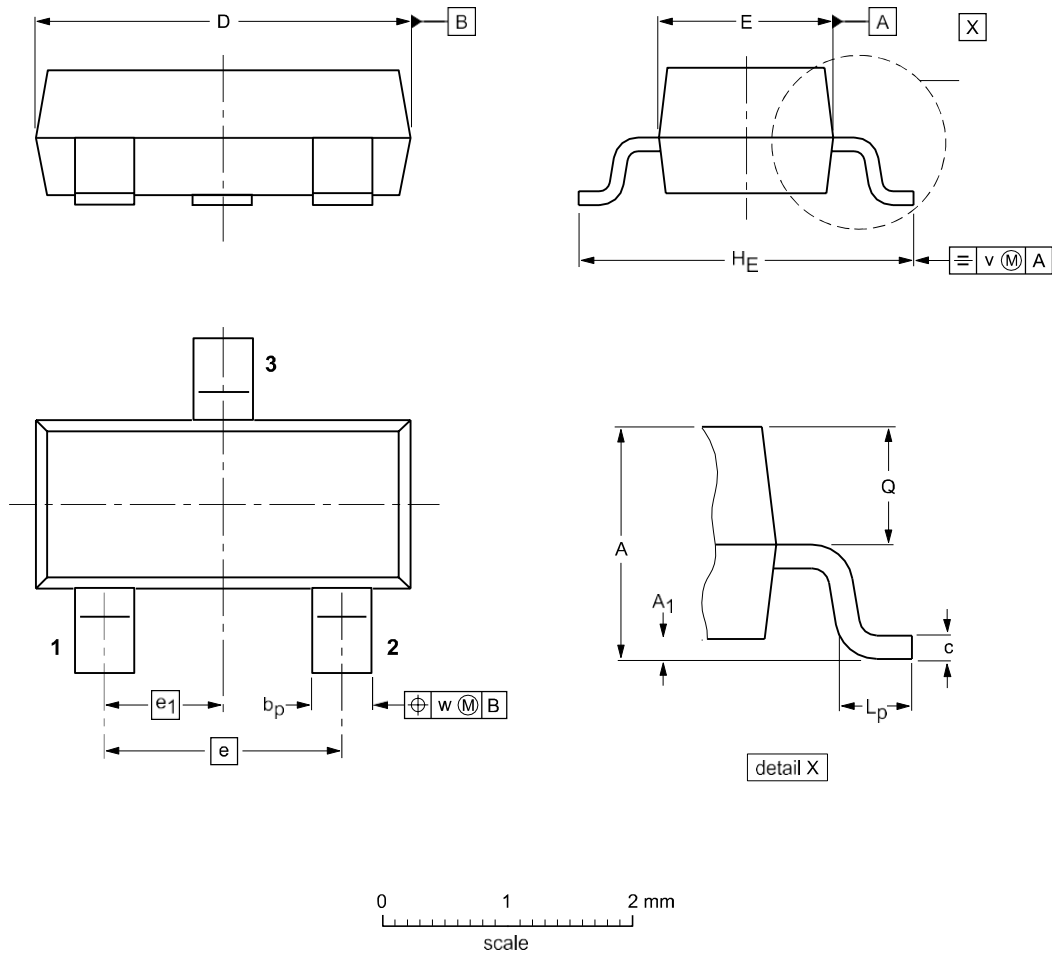




Note: The above characteristics curves are presented for reference only and not guaranteed by production test.



■ SOT-23



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max.	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.9	0.1	0.48 0.38	0.15 0.09	3.0 2.8	1.4 1.2	1.9	0.95	2.5 2.1	0.45 0.15	0.55 0.45	0.2	0.1

